京鼎精密科技股份有限公司

2026 Second Quarter Investor Presentation

2026/09/09

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Agenda

- Company Profile
- Financial Reports
- Business Performance and Outlook
- Q&A

Foxsemicon Integrated Technology, Inc.(Fiti)

Bob Chen Chairman

Kevin Chiu CEO

Business

- Key components and modules for semiconductor front-end equipment manufacturing.
- Semiconductor equipment, spare parts, and repair services
- R&D, Sales, and Total solutions provider for semi equipment
- Medical imaging equipment manufacturing and design services.

Global Footprint

2001 Founded

2015 Listed (3413 TT)

4,524 Employees
As of 2026/06/30

NT$1.108 bn Capital
As of 2026/06/03

NT$36.607 bn Market Cap
As of 2026/06/30

1H26 Revenue	1H26 Gross Margin	1H26 EPS
NT$11.861 bn	23.0%	NT$8.89
+17.8% YoY	-3.7 ppt YoY	-12.1% YoY

Global Footprint

Manufacturing Footprint: 8 Sites in 4 Regions

HVM Site

Songjiang, CN	Kunshan, CN
	

HQ/ HVM Site

Chunan(HQ), TW	Chunan, TW	Hsinchu, TW
		

NPI Center

Silicon Valley, USA

HVM Site

Rayong, TH	Chonburi, TH
	

Sales & Service Office

San Jose/ Austin/ Phoenix, USA

Jiangsu

Shangha

Chunan HQ, TW

Thailand

Singapore

California

Arizona

Texas

- : HVM Site - Taiwan/ Thailand/ China
- : Sales & Service Office - Taiwan/ China/ USA
- : NPI R&D Center - USA

2Q26 Financial Reports

Consolidated Statements of Comprehensive Income

(NTD in millions)	2Q26		1Q26		QoQ%	2Q25		YoY%	1H26		1H25		YoY%
Revenues	6,300	100.0%	5,562	100.0%	13.3%	5,203	100.0%	21.1%	11,861	100.0%	10,072	100.0%	17.8%
Gross Profit	1,404	22.3%	1,326	23.8%	-1.5 ppts	1,358	26.1%	-3.8 ppts	2,730	23.0%	2,688	26.7%	-3.7 ppts
Operating expenses	(634)	(10.1%)	(599)	(10.7%)		(481)	(9.2%)		(1,233)	(10.4%)	(934)	(9.3%)	
Operating Income	769	12.2%	727	13.1%	-0.9 ppts	877	16.9%	-4.7 ppts	1,496	12.6%	1,754	17.4%	-4.8 ppts
Non-Operating Items	(76)	(1.2%)	34	0.6%		(456)	(8.8%)		(42)	(0.3%)	(372)	(3.7%)	
Income Before Tax	693	11.0%	761	13.7%	-2.7 ppts	421	8.1%	+2.9 ppts	1,454	12.3%	1,381	13.7%	-1.4 ppts
Net Income	555	8.8%	519	9.3%	-0.5 ppts	391	7.5%	+1.3 ppts	1,073	9.0%	1,115	11.1%	-2.1 ppts
Attributable to:													
Owners of the parent	511		473		8.0%	369		38.6%	984		1,093		-9.9%
Basic EPS(NTS)	4.61		4.28		0.33	3.41		1.20	8.89		10.11		(1.22)
Weighted-average outstanding shares(M)	110.79		110.64			108.17			110.71		108.04		

Balance Sheet & Key Financial Indices

(NTD in millions)	2Q26		1Q26		2Q25	
Cash, Current financial assets	7,218	24%	8,673	29%	7,543	29%
Accounts Receivable	2,758	9%	2,120	7%	1,815	7%
Inventory	5,671	19%	4,800	16%	3,904	15%
Long-term Investments	499	2%	342	1%	438	2%
Property, plant and equipment	10,466	35%	10,552	35%	8,016	31%
Intangible assets	1,534	5%	1,554	5%	2,425	9%
Total Assets	30,322	100%	30,215	100%	26,062	100%
Accounts Pabable	2,265	7%	2,063	7%	1,359	5%
Bank borrowings	5,526	18%	5,119	17%	2,829	11%
Bonds Pabable	-	0%	-	0%	222	1%
Current Liabilites	9,992	33%	10,971	36%	7,311	28%
Total Liabilities	12,291	41%	12,836	42%	10,077	39%
Total Shareholders' Equity	18,031	59%	17,379	58%	15,985	61%
Key Indices						
AR Turnover Days	33		30		32	
Days Sales of Inventory	105		103		99	
AP Turnover days	37		38		38	
Cash Cycle	101		95		93	
Current Ratio(X)	1.66		1.50		1.88	

Cash Flow Statement

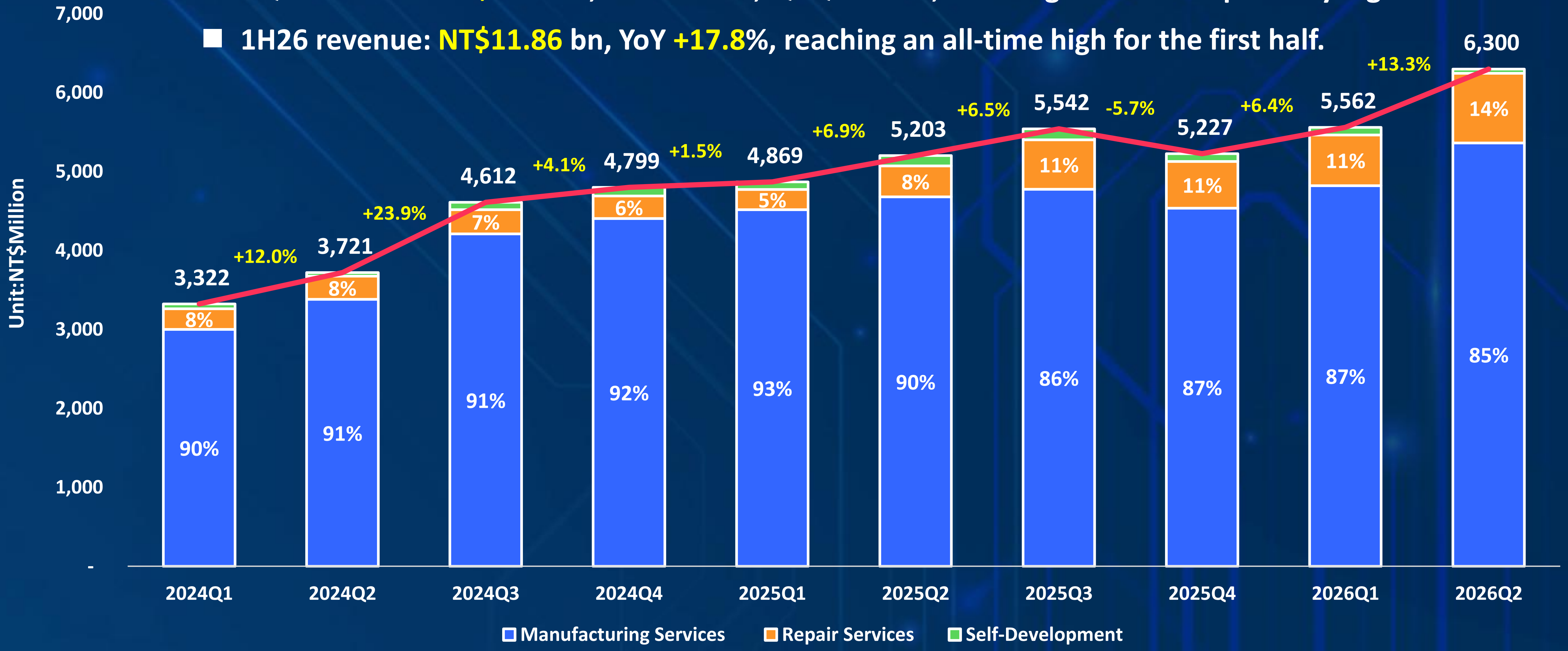
(NTD in millions)	1H26	1H25
Beginning Balance	6,626	7,527
Cash Flows from (Used in) Operating Activities	(99)	414
Capital expenditures	(1,441)	(2,119)
Cash dividends	(1,217)	-
Net cash payments for business combination	-	(1,263)
Time deposits	707	276
Net Change in Debt	1,861	908
Others	78	(65)
Ending Balance	6,515	5,678
Free Cash Flow*	(1,540)	(1,705)

*Free Cash Flow=Cash from operating activities-Capital expenditures

Business Performance and Outlook

Consolidated Revenue Trends

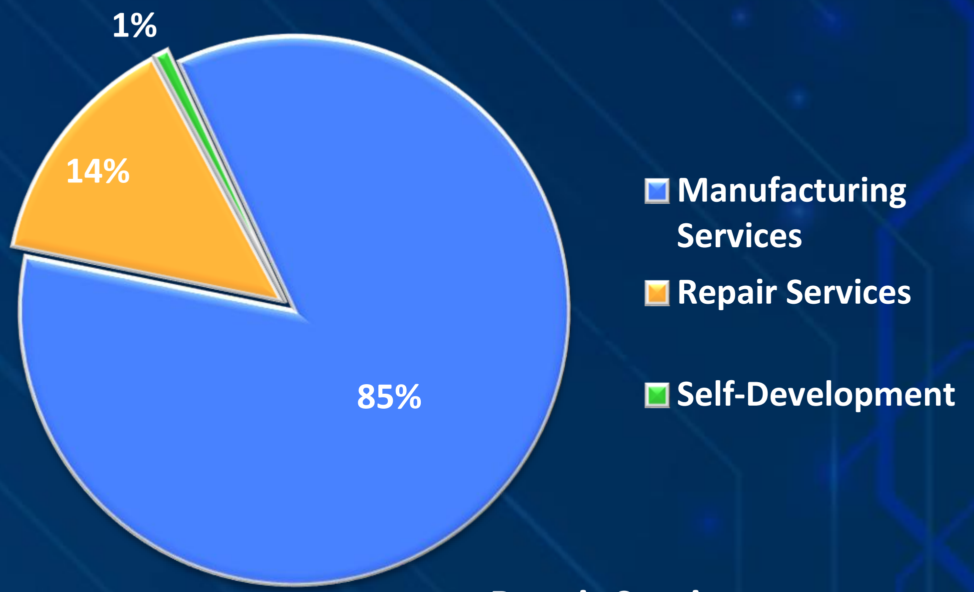
- 2Q26 revenue: **NT$6.30** bn, YoY **+21.1%**, QoQ **+13.3%**, reaching an all-time quarterly high.
- 1H26 revenue: **NT$11.86** bn, YoY **+17.8%**, reaching an all-time high for the first half.



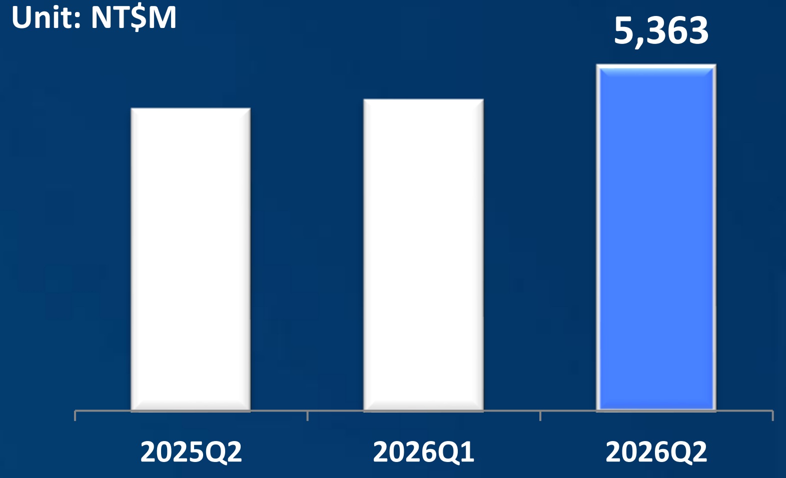
Note:

Manufacturing Services = Semiconductor key modules, key components & spare parts ； Repair Services = Semiconductor & aerospace repair
Self-Development = Semiconductor automation equipment

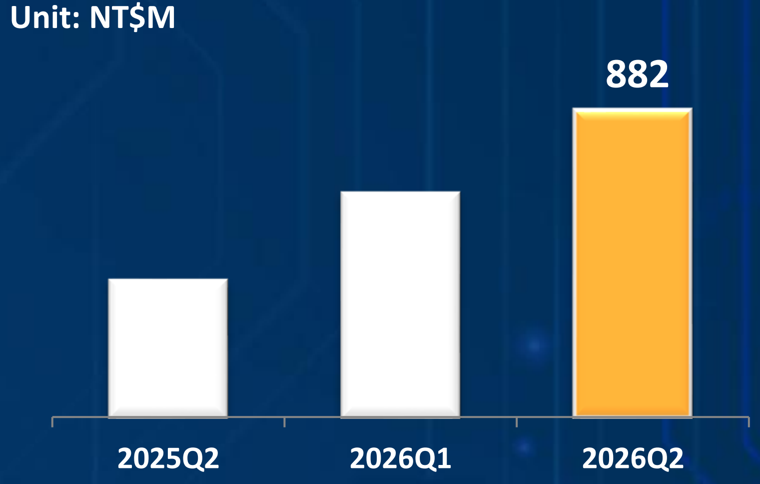
2Q26 Revenue by Business Segment



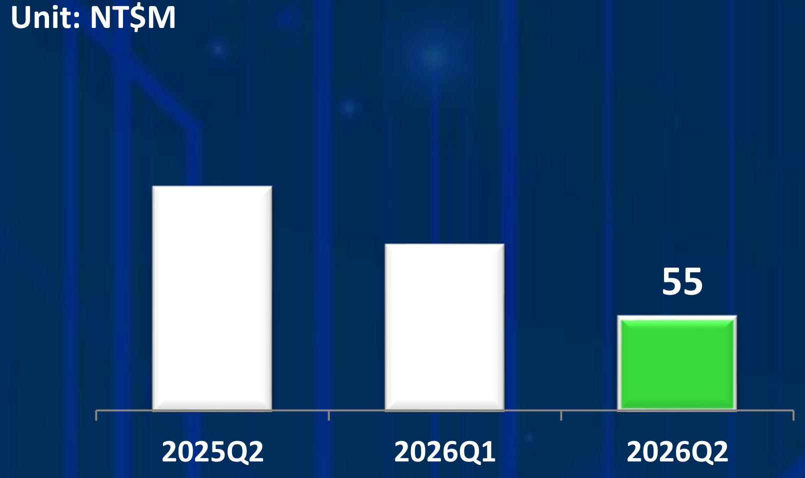
Manufacturing Services
+11.2% QoQ
+14.6% YoY



Repair Services
+37.2% QoQ
+124.7% YoY

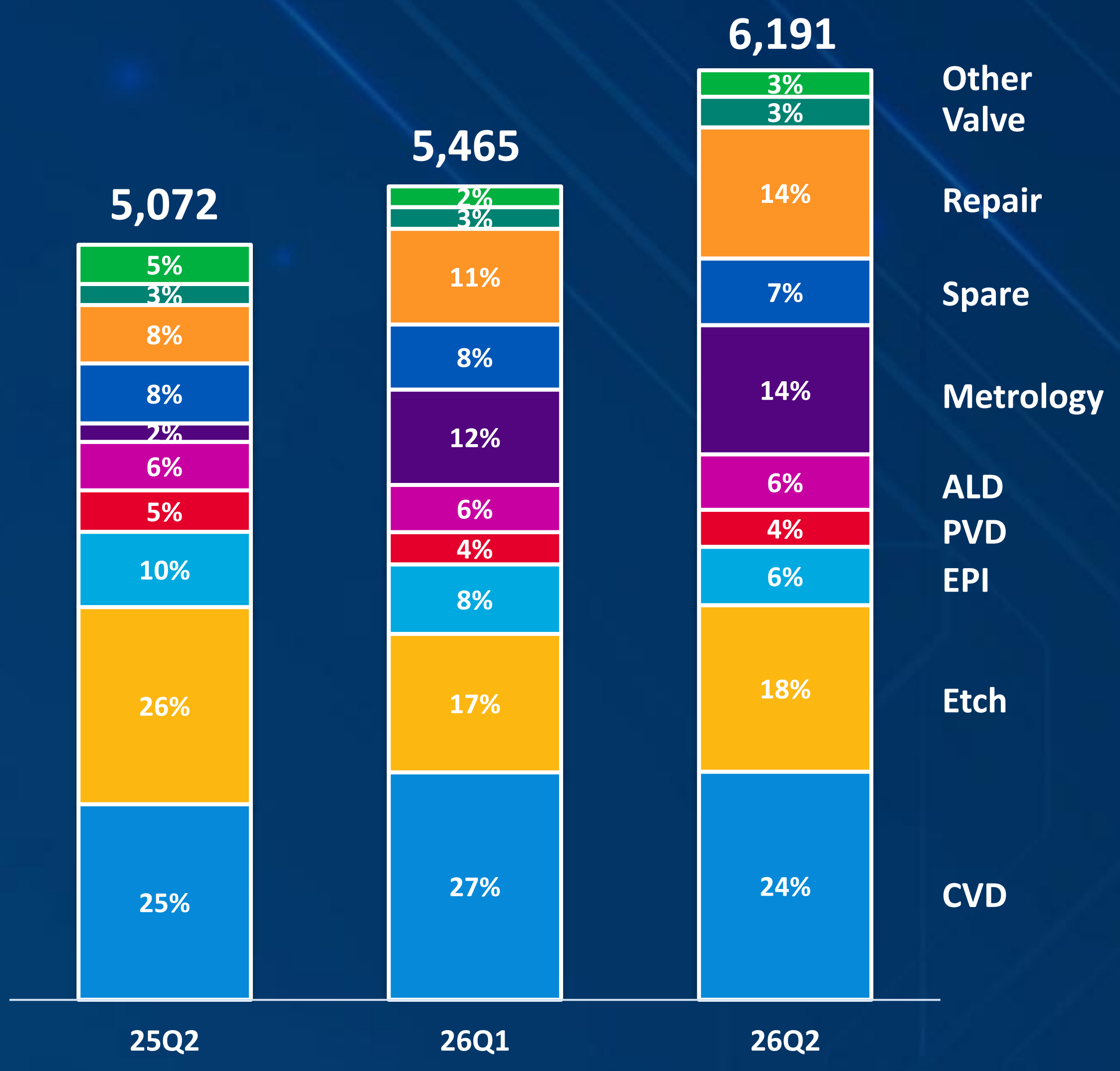


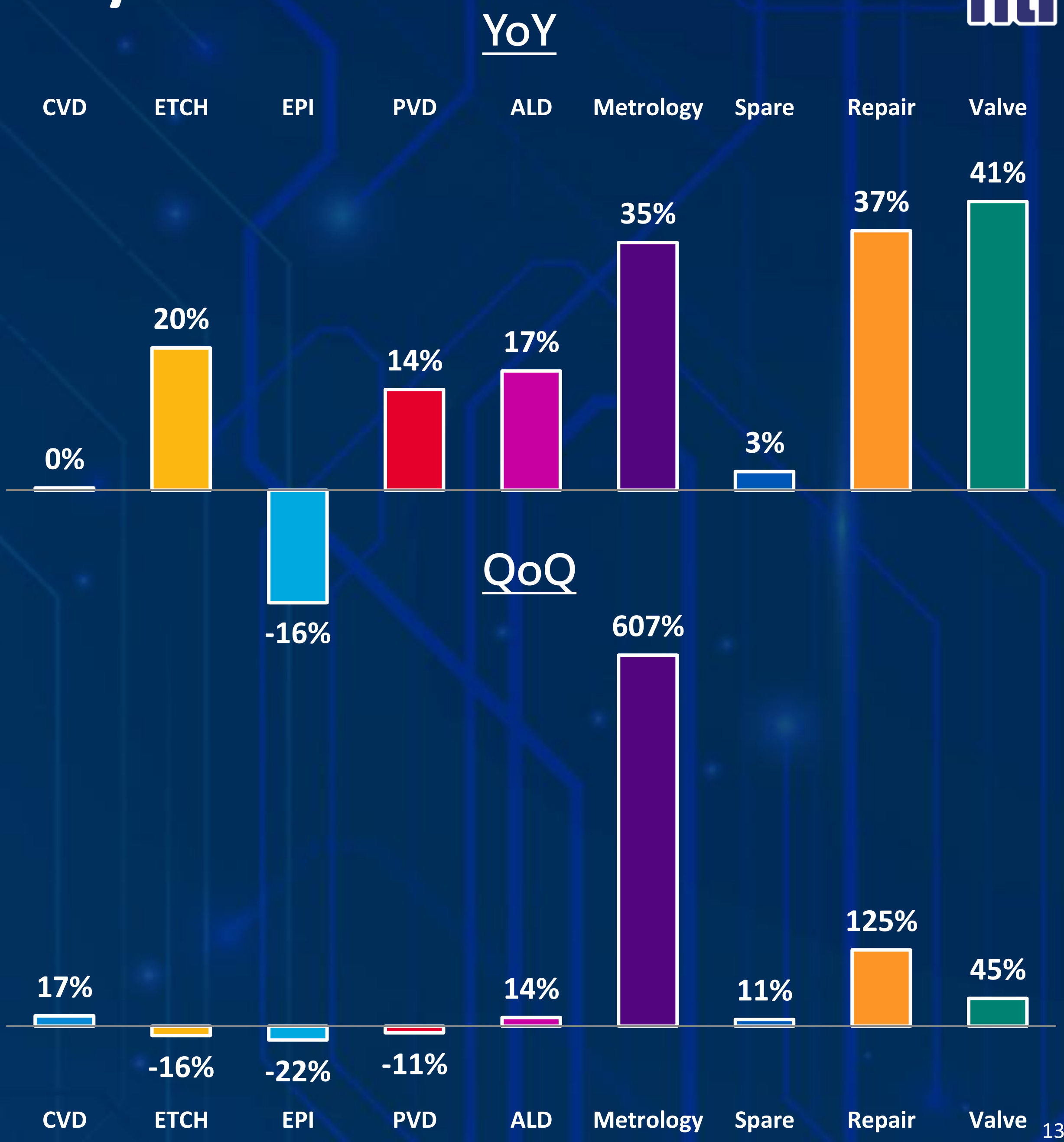
Self-Development
-43.6% QoQ
-58.3% YoY



2Q26 Manufacturing & Repair Services by Product

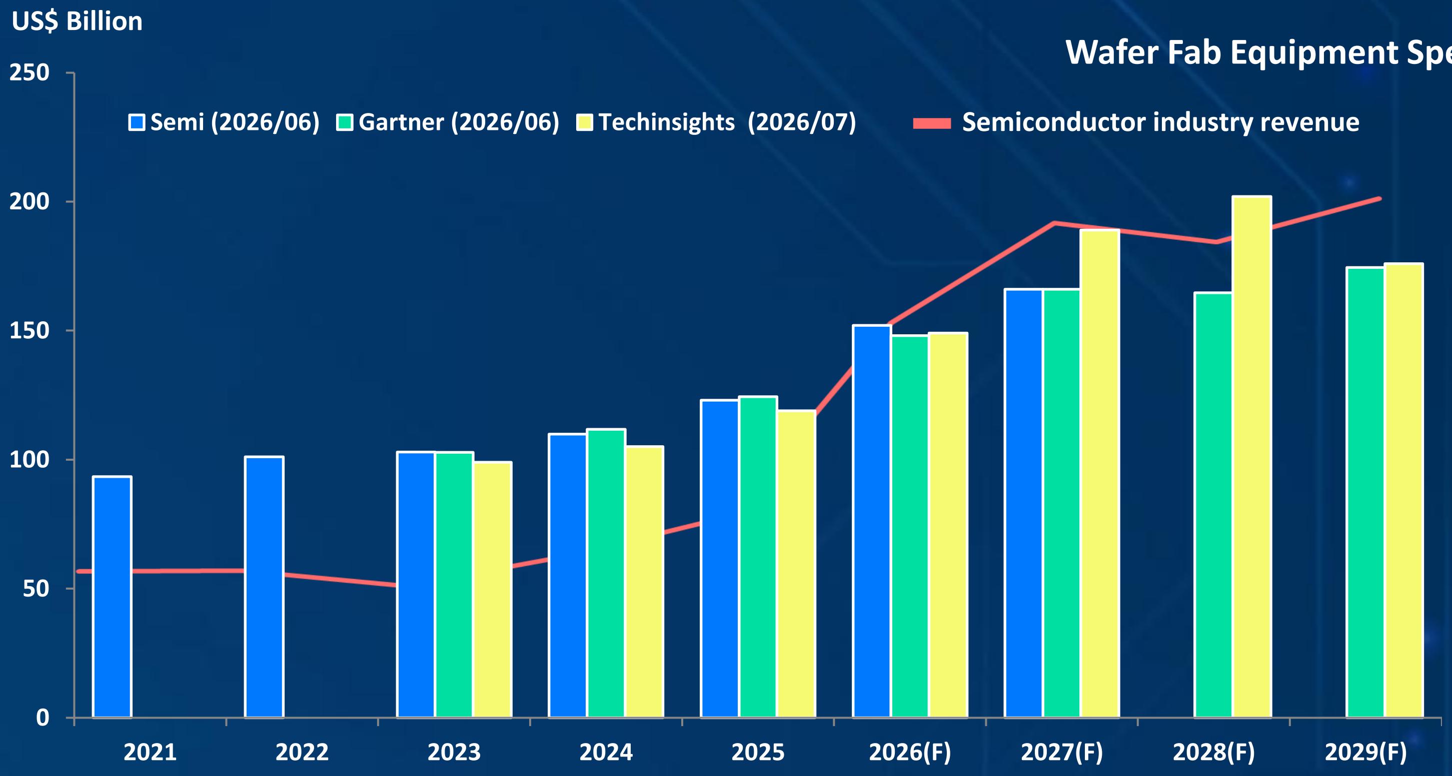
Unit:NT$Million





WFE Market

- The 2026 WFE market outlook continues to be revised upward, with growth currently estimated at approximately 19%–25%. Continued growth in AI demand, ongoing advances in semiconductor technologies, and fab capacity expansion are further driving equipment investment.
- The WFE market is expected to continue growing in 2027, supported by ongoing fab capacity expansion and equipment investment plans. Beyond 2028, the WFE market is expected to remain at a high level.
- As advanced process technologies, advanced memory, and advanced packaging continue to evolve, increasing process and chip complexity is driving greater demand for key semiconductor equipment used in deposition, etch, and metrology.



WFE($B)	2025	2026(F)	2027(F)	2028(F)	2029(F)
SEMI (2026/6)	123	152	166		
YoY	12%	24%	9%		
Gartner (2026/6)	124	148	166	165	174
YoY	11%	19%	12%	-1%	6%
TechInsights (2026/7)	119	149	189	202	176
YoY	13%	25%	27%	7%	-13%

Source:Semi/Gartner/TechInsights

FITI's Strategic Positioning and Market Opportunities

Serving Advanced Front-End and Advanced Packaging Through Vertically Integrated Manufacturing

Semiconductor Equipment Lifecycle Manufacturing Services

New Product Introduction (NPI)	Equipment Manufacturing		Aftermarket Spare Parts & Consumables	Refurbishment, Repair and Recycling	
NPI	Components & Modules	System Assembly	Spare Parts & Consumables	CMP Head Repair	Plasma Power Supply Repair

Comprehensive Vertically Integrated Manufacturing Capabilities

- High-end System Integration
- Precision Machining
- Special Treatment
- Frame & Sheet-metal Fabrication
- Quality Inspection & Metrology

Own Brand – Future Growth Drivers

Business Model & Market Positioning

Own-Brand Non-Process Automation Equipment and Micro-Contamination Prevention Equipment

Customers: Front-End Wafer Fabs and Wafer-Level Advanced Packaging & Test Facilities

Product Portfolio

- Micro Contamination Prevention Total Solutions
- Automated Reticle Transfer & Handling System
- Wafer Macro/ Micro Inspection Equipment
- Automated Wafer Transfer & Handling System

3Q26 Business Outlook

FITI	=	Manufacturing Services	+	Repair Services	+	Self-Development
QoQ →		QoQ →		QoQ →		QoQ ↗
YoY ↗		YoY ↗		YoY →		YoY ↗

Summary

Key Highlights

- 2Q26 revenue reached an all-time quarterly high, while 1H26 revenue reached an all-time high for the first half; 2H26 operating performance is expected to outperform 1H26.
- The Chon Buri plant in Thailand entered mass production in July; increasing production scale and improving manufacturing efficiency are expected to contribute to revenue and earnings growth
- With customers' medium- to long-term demand remaining strong, FITI approved its Phase II expansion in Thailand, with a planned investment of US$234 million to prepare for capacity needs beyond 2028.

Long-Term Growth Drivers

- **Continued WFE Market Expansion:**

  AI and HPC continue to drive structural growth in the global WFE market, supporting continued investment in advanced logic, memory, and advanced packaging.

- **Technology Advancements and Advanced Packaging Driving Equipment Demand:**

  Continued advancements in GAA, HBM, and advanced packaging technologies are increasing process and chip complexity, driving greater demand for key equipment such as deposition, etch, and inspection systems, where FITI has a strong presence.

- **Continued Product Diversification:**

  Demand for existing products continues to grow, while new product introduction (NPI) programs continue to increase, further expanding the company's growth drivers.

Q&A

Thank you